# SSD1357

# Advance Information

128 RGB x 128 Dot Matrix **OLED/PLED Segment/Common Driver with Controller** 



# Appendix: IC Revision history of SSD1357 Specification

Version	Change Items	Effective Date
0.10	1 <sup>st</sup> release	27-May-16
0.20	P. 9-10 Updated D_SEL and I <sub>REF</sub> in Pin Description P. 19 Updated 256 color depth description in GDDRAM P. 22 Updated SEG/COM Drivers description P. 26 Updated Power ON and OFF sequence description P. 28 Updated DC Characteristic parameters P. 29 Updated AC Characteristic parameters P. 35 Updated application example	23-Sep-16
1.0	Updated to Advance Information	09-Dec-16
	Gonfide Corporati	

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#### **GENERAL DESCRIPTION** 1

SSD1357 is a single-chip CMOS OLED/PLED driver with controller for organic/polymer light emitting diode dot-matrix graphic display. It consists of 384 segments and 128 commons output, supporting up to 128RGB x 128 dot matrix display. This IC is designed for Common Cathode type OLED/PLED panel.

SSD1357 has embedded Graphic Display Data RAM (GDDRAM). Data/Commands are sent from general MCU through the hardware selectable 8, 16 bits 6800-/8080-series compatible Parallel Interface, I<sup>2</sup>C Interface, or Serial Peripheral Interface. It supports 256-step contrast and 65K color control. SSD1357 is suitable for portable applications such as wearable electronics with vivid color OLED display.

#### 2 **FEATURES**

- Resolution: 128RGB x 128 dot matrix panel
- Power supply
  - (MCU interface logic level & low voltage power supply)  $V_{DD} = 1.65V - 3.5V$ poratio
  - $\circ$   $V_{CC} = 8.0V 18.0V$ (Panel driving power supply)
- Segment maximum source current: 320uA
- Common maximum sink current: 80mA
- Pin selectable MCU Interfaces:
  - o 8/16 bits 6800/8080-series parallel Interface
  - o 3/4 wire Serial Peripheral Interface
  - o I<sup>2</sup>C Interface
- 256 step brightness current control for the each color component plus 16 step master current
- Support color depth of 256 and 65k
- Support 3 individual Gamma Look Up Tables (GLUT) for R, G, B
- Color Swapping Function (RGB BGR)
- Row re-mapping and Column re-mapping
- Screen saving continuous scrolling function in both horizontal and vertical direction
- Screen saving infinite content scrolling function
- Programmable Frame Rate
- Power On Reset (POR)
- On-Chip Oscillator
- Chip layout for COG, COF
- Operating temperature range -40°C to 85°C

#### 3 ORDERING INFORMATION

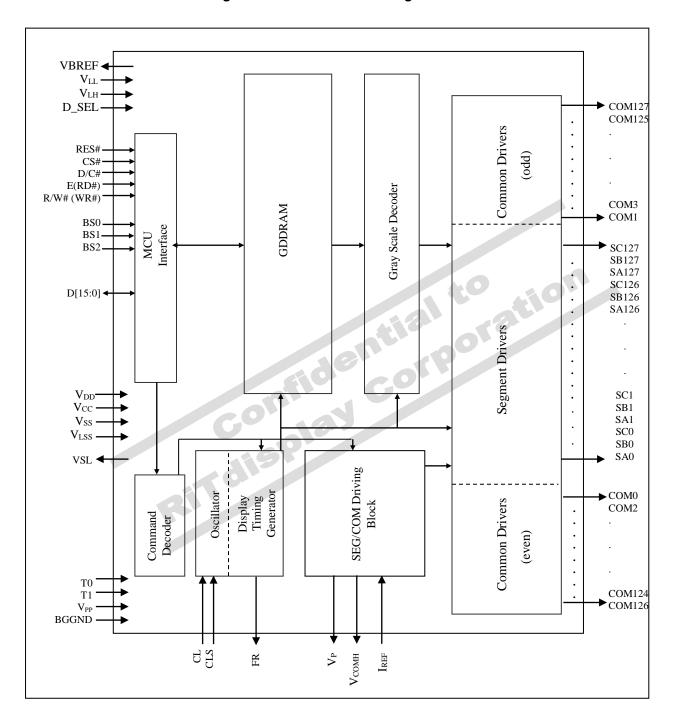
**Table 3-1: Ordering Information** 

Ordering Part Number	SEG	COM	Package Form	Remark				
				<ul> <li>Min SEG pad pitch : 27um</li> </ul>				
				<ul> <li>Min COM pad pitch : 33.4um</li> </ul>				
SSD1357Z	128RGB	128	COG	<ul> <li>Min I/O pad pitch : 55um</li> </ul>				
				o Die thickness: 250um				
				o Bump height: nominal 12um				

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# 4 BLOCK DIAGRAM

Figure 4-1: SSD1357 Block Diagram



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# 5 PIN DESCRIPTION

# Key:

I = Input	NC = Not Connected
O =Output	Pull LOW= connect to Ground
I/O = Bi-directional (input/output)	Pull HIGH= connect to V <sub>DD</sub>
P = Power pin	

Table 5-1: Pin description

Pin Name	Pin Type	Description
$V_{DD}$	P	Power supply pin for core logic operation. A capacitor should be connected between this pin and $V_{\rm SS}$ .
V <sub>CC</sub>	P	Power supply for panel driving voltage. This is also the most positive power voltage supply pin. A capacitor should be connected between this pin and $V_{\text{SS}}$ .
$V_p$	P	This pin is the segment pre-charge voltage reference pin. A capacitor can be connected between this pin and $V_{SS}$ to improve vision performance. No external power supply is allowed to connect to this pin.
ТО	P	Reserved pin. This pin should be kept NC.
T1	P	Reserved pin. This pin should be kept NC.
$V_{pp}$	P	Reserved pin. It must be connected to V <sub>DD</sub> .
BGGND	P	Reserved pin. It must be connected to V <sub>SS</sub> .
$V_{SS}$	P	Ground pin. It must be connected to external ground.
$V_{LSS}$	P	Analog system ground pin. It must be connected to external ground.
VSL	P	This is segment voltage (output low level) reference pin.  This pin has to connect with resistor and diode to ground (details depends on application).
$V_{LH}$	P	Logic high (same voltage level as $V_{\text{DD}}$ ) for internal connection of input and I/O pins. No need to connect to external power source.
$\overline{V_{LL}}$	P	Logic low (same voltage level as $V_{SS}$ ) for internal connection of input and I/O pins. No need to connect to external ground.
V <sub>COMH</sub>	P	COM signal deselected voltage level. A capacitor should be connected between this pin and $V_{\text{SS}}$ .
VBREF	O	This is a reserved pin. It should be kept NC.

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Pin Name	Pin Type	Description						
BS[2:0]	I	MCU bus interface selection pins. Select appropriate logic setting as described in the following table. BS2, BS1 and BS0 are pin select.						
		Table 5-2: Bus Interface selection						
		BS[2:0] Interface						
		000 4 line SPI						
		001 3 line SPI						
		010 I <sup>2</sup> C						
		100 8-bit 6800 parallel 101 16-bit 6800 parallel						
		110 8-bit 8080 parallel						
		111 16-bit 8080 parallel						
		Note						
		$^{(1)}$ 0 is connected to $V_{SS}$ $^{(2)}$ 1 is connected to $V_{DD}$						
$I_{REF}$	I	This pin is the segment output current reference pin.						
		$I_{REF}$ is supplied externally. A resistor should be connected between this pin and $V_{SS}$ to maintain the current around 10uA.						
CL	I	This is external clock input pin.						
		When internal clock is enabled (i.e. HIGH in CLS pin), this pin is not used and						
		should be connected to $V_{SS}$ . When internal clock is disabled (i.e. LOW in CLS pin),						
		this pin is the external clock source input pin.						
CLS	I	This is internal clock enable pin.						
		When it is pulled HIGH (i.e. connect to $V_{DD}$ ), internal clock is enabled. When it is pulled LOW, the internal clock is disabled; an external clock source must be connected to the CL pin for normal operation.						
CS#	I	This pin is the chip select input connecting to the MCU.						
CS#		The chip is enabled for MCU communication only when CS# is pulled LOW (active LOW).						
RES#	I	This pin is reset signal input.						
		When the pin is pulled LOW, initialization of the chip is executed.  Keep this pin pull HIGH during normal operation.						
D/C#	I	This pin is Data/Command control pin connecting to the MCU.						
		When the pin is pulled HIGH, the data at D[15:0] will be interpreted as data. When the pin is pulled LOW, the data at D[15:0] will be transferred to a command register. In I $^2$ C mode, this pin acts as SA0 for slave address selection. When 3-wire serial interface is selected, this pin must be connected to $V_{SS}$ .						

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Pin Type	Description
I	This pin is read / write control input pin connecting to the MCU interface.
	When 6800 interface mode is selected, this pin will be used as Read/Write (R/W#) selection input. Read mode will be carried out when this pin is pulled HIGH and write mode when LOW. When 8080 interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled LOW and the chip is selected. When serial or $I^2C$ interface is selected, this pin must be connected to $V_{SS}$ .
	When serial of 1 c interface is selected, this pin must be connected to 455.
I	This pin is MCU interface input.
	When 6800 interface mode is selected, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled HIGH and the chip is selected.
	When 8080 interface mode is selected, this pin receives the Read (RD#) signal. Read operation is initiated when this pin is pulled LOW and the chip is selected.
	When serial or I <sup>2</sup> C interface is selected, this pin must be connected to V <sub>SS</sub> .
I/O	These pins are bi-directional data bus connecting to the MCU data bus. Unused pins are recommended to tie LOW.
	When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1 will be the serial data input: SDIN.
	When I <sup>2</sup> C mode is selected, D2, D1 should be tied together and serve as SDA <sub>out</sub> , SDA <sub>in</sub> in application and D0 is the serial clock input, SCL.
I	Should be connected to $V_{SS}$ .
0	This pin outputs RAM write synchronization signal. Proper timing between MCU data writing and frame display timing can be achieved to prevent tearing effect. It should be kept NC if it is not used.
O	These pins provide the OLED segment driving signals. These pins are $V_{SS}$ state when display is OFF.
	The 384 segment pins are divided into 3 groups, SA, SB and SC. Each group can have different color settings for color A, B and C.
0	These pins provide the Common switch signals to the OLED panel.
-	This is dummy pin. It should be kept NC.
	I

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#### 6 FUNCTIONAL BLOCK DESCRIPTIONS

#### 6.1 MCU Interface selection

SSD1357 MCU interface consist of 16 data pins and 5 control pins. The pin assignment at different interface mode is summarized in Table 6-1. Different MCU mode can be set by hardware selection on BS[2:0] pins (please refer to Table 5-1: Pin description for BS[2:0] setting).

Table 6-1: MCU interface assignment under different bus interface mode

Pin Name Bus	Data/Command Interface										Control Signal										
Interface	D15	D14	D13	D12	D11	D10	D9	D8	D7	7 D6	D5	D4	D3	D2	D1	D0	E	R/W#	CS#	D/C#	RES#
8-bit 8080		Tie Low							-			D[7:	0]			RD#	WR#	CS#	D/C#	RES#	
8-bit 6800		Tie Low								D[7:0]					Е	R/W#	CS#	D/C#	RES#		
16-bit 8080								D[1	5:0	)]							RD#	WR#	CS#	D/C#	RES#
16-bit 6800								D[1	5:0	)]							Е	R/W#	CS#	D/C#	RES#
3-wire SPI		Tie Low												SDIN	SCLK	Tie	e Low	CS#	Tie Low	RES#	
4-wire SPI	Tie Low						)W		SDIN SCLK			SCLK	Tie	e Low	CS#	D/C#	RES#				
$I^2C$						Tie I	Low		SDA <sub>OUT</sub> SDA <sub>IN</sub> SCL				Tie Low		SA0	RES#					

# 6.1.1 MCU Parallel 6800-series Interface

The parallel interface consists of 16 bi-directional data pins (D[15:0]), R/W#, D/C#, E and CS#.

A LOW in R/W# indicates WRITE operation and HIGH in R/W# indicates READ operation. A LOW in D/C# indicates COMMAND read/write and HIGH in D/C# indicates DATA read/write. The E input serves as data latch signal while CS# is LOW. Data is latched at the falling edge of E signal.

Table 6-2: Control pins of 6800 interface

Function	E	R/W#	CS#	D/C#
Write command	<b>\</b>	L	L	L
Read status	1	Н	L	L
Write data	$\downarrow$	L	L	Н
Read data	$\downarrow$	Н	L	Н

#### Note

H stands for HIGH in signal

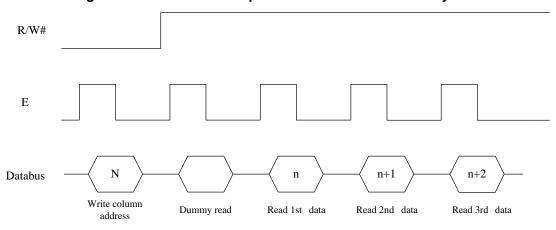
L stands for LOW in signal

In order to match the operating frequency of display RAM with that of the microprocessor, some pipeline processing is internally performed which requires the insertion of a dummy read before the first actual display data read. This is shown in Figure 6-1.

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<sup>(1) \</sup>preceq stands for falling edge of signal

Figure 6-1: Data read back procedure - insertion of dummy read



# 6.1.2 MCU Parallel 8080-series Interface

The parallel interface consists of 16 bi-directional data pins (D[15:0]), RD#, WR#, D/C# and CS#.

A LOW in D/C# indicates COMMAND read/write and HIGH in D/C# indicates DATA read/write. A rising edge of RD# input serves as a data READ latch signal while CS# is kept LOW. A rising edge of WR# input serves as a data/command WRITE latch signal while CS# is kept LOW.

Figure 6-2: Example of Write procedure in 8080 parallel interface mode

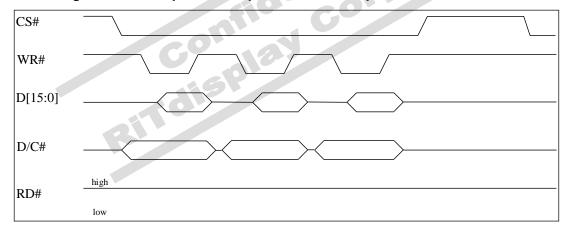
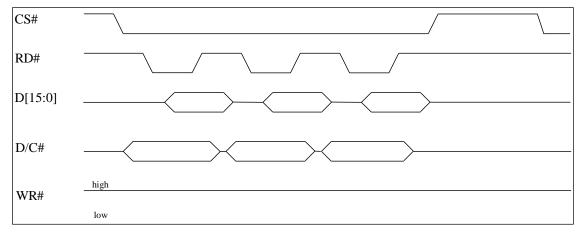


Figure 6-3 : Example of Read procedure in 8080 parallel interface mode



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Table 6-3: Control pins of 8080 interface

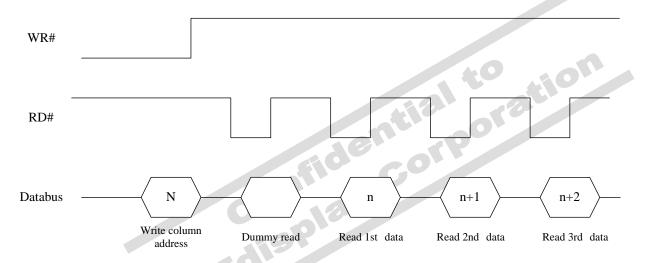
Function	RD#	WR#	CS#	D/C#
Write command	Н	<b>↑</b>	L	L
Read status	<b>↑</b>	Н	L	L
Write data	Н	<b>↑</b>	L	Н
Read data	1	Н	L	Н

#### Note

- (1) ↑ stands for rising edge of signal
- (2) H stands for HIGH in signal
- (3) L stands for LOW in signal

In order to match the operating frequency of display RAM with that of the microprocessor, some pipeline processing is internally performed which requires the insertion of a dummy read before the first actual display data read. This is shown in Figure 6-4.

Figure 6-4: Display data read back procedure - insertion of dummy read



# 6.1.3 MCU Serial Interface (4-wire SPI)

The 4-wire serial interface consists of serial clock: SCLK, serial data: SDIN, D/C#, CS#. In 4-wire SPI mode, D0 acts as SCLK, D1 acts as SDIN. For the unused data pins from D2 to D7, E(RD#) and R/W#(WR#) can be connected to an external ground.

Table 6-4: Control pins of 4-wire Serial interface

Function	E	<b>R/W</b> #	CS#	<b>D</b> /C#	<b>D</b> 0
Write command	Tie LOW	Tie LOW	L	L	<b>↑</b>
Write data	Tie LOW	Tie LOW	L	Н	<b>↑</b>

#### Note

- (1) H stands for HIGH in signal
- (2) L stands for LOW in signal
- (3) ↑ stands for rising edge of signal

SDIN is shifted into an 8-bit shift register on every rising edge of SCLK in the order of D7, D6, ... D0. D/C# is sampled on every eight clocks and the data byte in the shift register is written to the Graphic Display Data RAM (GDDRAM) or command register in the same clock. D/C# should keep its stage from the start to the end of operation.

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Under serial mode, only write operations are allowed.

CS# D/C# SDIN/ DB2 DB1 DBn **SCLK** SCLK (D0) D7 D5 D3 SDIN(D1) D6 D2 D0

Figure 6-5: Write procedure in 4-wire Serial interface mode

The 3-wire serial interface consists of serial clock SCLK, serial data SDIN and CS#.

In 3-wire SPI mode, D0 acts as SCLK, D1 acts as SDIN. For the warm (WR#), E(RD#) and D/C# com 1 In 3-wire SPI mode, D0 acts as SCLK, D1 acts as SDIN. For the unused data pins from D2 to D7, R/W#

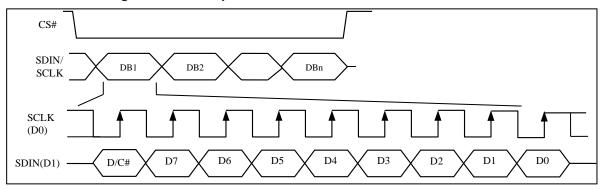
The operation is similar to 4-wire serial interface while D/C# pin is not used. There are altogether 9-bits will be shifted into the shift register on every ninth clock in sequence: D/C# bit, D7 to D0 bit. The D/C# bit (first bit of the sequential data) will determine the following data byte in the shift register is written to the Display Data RAM (D/C# bit = 1) or the command register (D/C# bit = 0).

Under serial mode, only write operations are allowed.

Table 6-5: Control pins of 3-wire Serial interface

Function	E(RD#)	<b>R/W</b> #( <b>WR</b> #)	CS#	D/C#	<b>D0</b>	Note
Write command	Tie LOW	Tie LOW	L	Tie LOW	1	(1) L stands for LOW in signal
Write data	Tie LOW	Tie LOW	L	Tie LOW	1	(2) ↑ stands for rising edge of signal

Figure 6-6: Write procedure in 3-wire Serial interface mode



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# 6.1.5 MCU I<sup>2</sup>C Interface

The  $I^2C$  communication interface consists of slave address bit SA0,  $I^2C$ -bus data signal SDA (SDA<sub>OUT</sub>/D<sub>2</sub> for output and SDA<sub>IN</sub>/D<sub>1</sub> for input) and  $I^2C$ -bus clock signal SCL (D<sub>0</sub>). Both the data and clock signals must be connected to pull-up resistors. RES# is used for the initialization of device.

#### a) Slave address bit (SA0)

SSD1357 has to recognize the slave address before transmitting or receiving any information by the I<sup>2</sup>C-bus. The device will respond to the slave address following by the slave address bit ("SA0" bit) and the read/write select bit ("R/W#" bit) with the following byte format,

b<sub>7</sub> b<sub>6</sub> b<sub>5</sub> b<sub>4</sub> b<sub>3</sub> b<sub>2</sub> b<sub>1</sub> b<sub>0</sub> 0 1 1 1 1 0 SA0 R/W#

"SA0" bit provides an extension bit for the slave address. Either "0111100" or "0111101", can be selected as the slave address of SSD1357. D/C# pin acts as SA0 for slave address selection. "R/W#" bit is used to determine the operation mode of the I<sup>2</sup>C-bus interface. R/W#=1, it is in read mode. R/W#=0, it is in write mode.

#### b) I<sup>2</sup>C-bus data signal (SDA)

SDA acts as a communication channel between the transmitter and the receiver. The data and the acknowledgement are sent through the SDA.

It should be noticed that the ITO track resistance and the pulled-up resistance at "SDA" pin becomes a voltage potential divider. As a result, the acknowledgement would not be possible to attain a valid logic 0 level in "SDA".

"SDA<sub>IN</sub>" and "SDA<sub>OUT</sub>" are tied together and serve as SDA. The "SDA<sub>IN</sub>" pin must be connected to act as SDA. The "SDA<sub>OUT</sub>" pin may be disconnected. When "SDA<sub>OUT</sub>" pin is disconnected, the acknowledgement signal will be ignored in the  $I^2C$ -bus.

# c) I<sup>2</sup>C-bus clock signal (SCL)

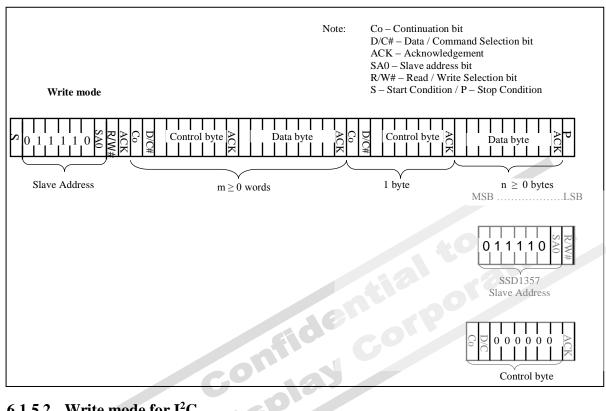
The transmission of information in the  $I^2C$ -bus is following a clock signal, SCL. Each transmission of data bit is taken place during a single clock period of SCL.

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### 6.1.5.1 I<sup>2</sup>C-bus Write data

The I<sup>2</sup>C-bus interface gives access to write data and command into the device. Please refer to Figure 6-7 for the write mode of I<sup>2</sup>C-bus in chronological order.

Figure 6-7: I<sup>2</sup>C-bus data format



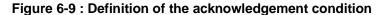
# 6.1.5.2 Write mode for $I^2C$

- 1) The master device initiates the data communication by a start condition. The definition of the start condition is shown in Figure 6-8. The start condition is established by pulling the SDA from HIGH to LOW while the SCL stays HIGH.
- 2) The slave address is following the start condition for recognition use. For the SSD1357, the slave address is either "b0111100" or "b0111101" by changing the SA0 to LOW or HIGH (D/C pin acts as SA0).
- 3) The write mode is established by setting the R/W# bit to logic "0".
- 4) An acknowledgement signal will be generated after receiving one byte of data, including the slave address and the R/W# bit. Please refer to the
- 5) Figure 6-9 for the graphical representation of the acknowledge signal. The acknowledge bit is defined as the SDA line is pulled down during the HIGH period of the acknowledgement related clock pulse.
- 6) After the transmission of the slave address, either the control byte or the data byte may be sent across the SDA. A control byte mainly consists of Co and D/C# bits following by six "0" 's.
  - a. If the Co bit is set as logic "0", the transmission of the following information will contain data bytes only.
  - The D/C# bit determines the next data byte is acted as a command or a data. If the D/C# bit is set to logic "0", it defines the following data byte as a command. If the D/C# bit is set to logic "1", it defines the following data byte as a data which will be stored at the GDDRAM. The GDDRAM column address pointer will be increased by one automatically after each data write.
- 7) Acknowledge bit will be generated after receiving each control byte or data byte.
- 8) The write mode will be finished when a stop condition is applied. The stop condition is also defined in Figure 6-8. The stop condition is established by pulling the "SDA in" from LOW to HIGH while the "SCL" stays HIGH.

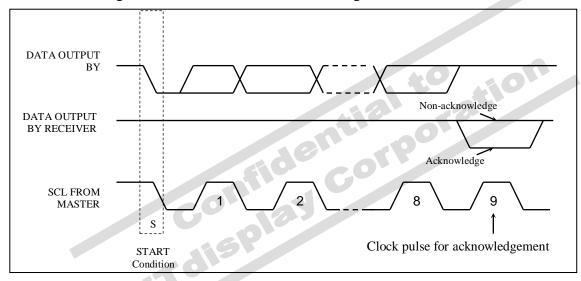
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 $t_{HSTART}$  $t_{SSTOP}$ **SDA** SDA SCL SCL START condition

Figure 6-8: Definition of the Start and Stop Condition



STOP condition



Please be noted that the transmission of the data bit has some limitations.

- 1. The data bit, which is transmitted during each SCL pulse, must keep at a stable state within the "HIGH" period of the clock pulse. Please refer to the Figure 6-10 for graphical representations. Except in start or stop conditions, the data line can be switched only when the SCL is LOW.
- 2. Both the data line (SDA) and the clock line (SCL) should be pulled up by external resistors.

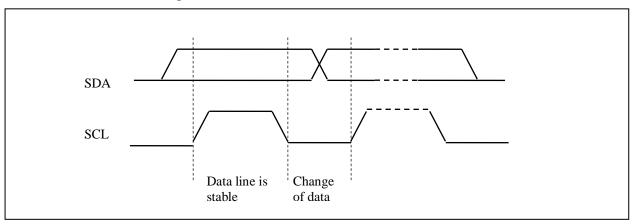


Figure 6-10: Definition of the data transfer condition

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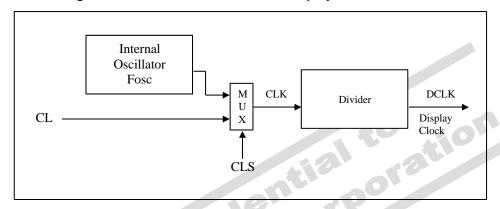
#### 6.2 Command Decoder

This module determines whether the input data is interpreted as data or command. Data is interpreted based upon the input of the D/C# pin.

If D/C# pin is HIGH, D[7:0] is interpreted as display data written to Graphic Display Data RAM (GDDRAM). If it is LOW, the input at D[7:0] is interpreted as a command. Then data input will be decoded and written to the corresponding command register.

# 6.3 Oscillator Circuit and Display Time Generator

Figure 6-11: Oscillator Circuit and Display Time Generator



This module is an on-chip LOW power RC oscillator circuitry. The operation clock (CLK) can be generated either from internal oscillator or external source CL pin. This selection is done by CLS pin. If CLS pin is pulled HIGH, internal oscillator is chosen and CL should be connected to  $V_{SS}$ . Pulling CLS pin LOW disables internal oscillator and external clock must be connected to CL pins for proper operation. When the internal oscillator is selected, its output frequency Fosc can be changed by command B3h A[7:4].

The display clock (DCLK) for the Display Timing Generator is derived from CLK. The division factor "D" can be programmed from 1 to 256 by command B3h

$$DCLK = F_{OSC} / D$$

The frame frequency of display is determined by the following formula.

$$F_{FRM} = \frac{F_{osc}}{D \times K \times No. \text{ of } Mux}$$

where

- D stands for clock divide ratio. It is set by command B3h A[3:0]. The divide ratio has the range from 1 to 256
- K is the number of display clocks per row. The value is derived by

 $K = Phase 1 period + Phase 2 period + K_o$ 

= 8 + 16 + 145 = 169 at power on reset (that is  $K_0$  is a constant that equals to 145)

Please refer to Section 6.7 "SEG / COM Drivers" for the details of the "Phase".

- Number of multiplex ratio is set by command CAh. The power on reset value is 127 (i.e. 128MUX).
- F<sub>OSC</sub> is the oscillator frequency. It can be changed by command B3h A[7:4]. The higher the register setting results in higher frequency.

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#### **6.4** Reset Circuit

When RES# input is LOW, the chip is initialized with the following status:

- 1. Display is OFF
- 2. 128 MUX Display Mode
- 3. Normal segment and display data column address and row address mapping (SEG0 mapped to address 00h and COM0 mapped to address 00h)
- 4. Shift register data clear in serial interface
- 5. Display start line is set at display RAM address 0
- 6. Column address counter is set at 0
- 7. Normal scan direction of the COM outputs
- 8. Command A2h, B1h, B3h, BBh, BEh are locked by command FDh

#### 6.5 GDDRAM

# 6.5.1 GDDRAM structure

SA0

SEG output

SB0

SC0

SA1

SB1

SC1

SA2

.....

.....

SC126

SA127 SB127

The GDDRAM is a bit mapped static RAM holding the pattern to be displayed. The RAM size is 128 x 128 x 16bits. For mechanical flexibility, re-mapping on both Segment and Common outputs can be selected by software. Each pixel has 16-bit data. Sub-pixels for color A, C have 5 bits and B have 6 bits. The arrangement of data pixel in graphic display data RAM is shown in Table 6-6.

0 2 125 Segment Normal 126 Address Remapped 127 126 1 Color В В Α CВ Data format B5 B5 ..... В5 C4 A4 В4 Α4 C4 **B**3 **B**3 C3 C3 В3 A3 Common A2 B2 C2 A2 B2 C2 A2 C2 A2 B2 C2 C1 Address A1 B1 C1 A1 В1 A1 C1 A1 В1 C1 A0 В0 C0 В0 C0 A0 ..... C0 A0 В0 C0 A0 Normal Remapped 126 6 6 125 6 6 6 124 4 123 6 ..... 6 122 6 ..... 6 121 120 no. of bits in this cell 6 6 ..... 123 6 6 ..... 6 125 6 6 ••••• 6 126 6 6

Table 6-6: 65k Color Depth Graphic Display Data RAM Structure

Common
output
COM0
COM1
COM2
COM3
COM4
COM5
COM6
COM7
:
:
:
:
COM124
COM125
COM126
COM127

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# 6.5.2 Data bus to RAM mapping under different input mode

Table 6-7: Write Data bus usage under different bus width and color depth mode

	Write data								Da	ta bu	s							
Bus width	Color depth	Input order	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
8bits / Serial	256		X	X	X	X	X	X	X	X	C4	C3	C2	B5	B4	В3	A4	A3
8bits / Serial	65k	1st	X	X	X	X	X	X	X	X	C4	C3	C2	C1	C0	B5	B4	В3
outs / Serial	UJK	2nd	X	X	X	X	X	X	X	X	B2	B1	B0	A4	A3	A2	A1	A0
		1st	X	X	X	X	X	X	X	X	X	X	C4	C3	C2	C1	C0	X
8bits / Serial	Pseudo 262k	2nd	X	X	X	X	X	X	X	X	X	X	B5	B4	В3	B2	B1	B0
		3rd	X	X	X	X	X	X	X	X	X	X	A4	A3	A2	A1	A0	X
16bits	65k		C4	C3	C2	C1	C0	B5	B4	B3	B2	B1	B0	A4	A3	A2	A1	A0
16bits	Pseudo	1st	X	X	X	X	X	X	X	X	X	X	C4	C3	C2	C1	C0	X
Tooks	262k format 1	2nd	X	X	B5	B4	В3	B2	B1	B0	X	X	A4	A3	A2	A1	A0	X
	,	1st	X	X	C14	C13	C12	C11	C10	X	X	X	B15	B14	B13	B12	B11	<b>B</b> 10
16bits	Pseudo 262k format 2	2nd	X	X	A14	A13	A12	A11	A10	X	X	X	C24	C23	C22	C21	C20	X
	202K IOIIIAt 2	3rd	X	X	B25	B24	B23	B22	B21	B20	X	X	A24	A23	A22	A21	A20	X

Table 6-8: Read Data bus usage under different bus width and color depth mode

	Read data							0.0	Da	ta bu	s		Û					
Bus width	Color depth	Input order	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
8bits / Serial	256		X	X	X	X	X	X	X	X	C4	C3	C2	B5	B4	В3	A4	A3
8bits / Serial	65k	1st	X	X	X	X	X	X	X	X	C4	C3	C2	C1	C0	B5	B4	В3
ooks / Seriai	UJK	2nd	X	X	X	X	X	X	X	X	B2	B1	B0	A4	A3	A2	A1	A0
		1st	X	$\langle X \rangle$	X	X	X	X	X	X	X	X	C4	C3	C2	C1	C0	X
8bits / Serial	Pseudo 262k	2nd	X	X	X	X	X	X	X	X	X	X	B5	B4	В3	B2	B1	B0
		3rd	X	X	X	X	X	X	X	X	X	X	A4	A3	A2	A1	A0	X
16bits	65k		C4	C3	C2	C1	C0	B5	B4	В3	B2	B1	B0	A4	A3	A2	A1	A0
16bits	Pseudo	1st	X	X	X	X	X	X	X	X	X	X	C4	C3	C2	C1	C0	X
Tooles	262k format 1	2nd	X	X	B5	B4	В3	B2	B1	B0	X	X	A4	A3	A2	A1	A0	X
	ъ 1	1st	X	X	C14	C13	C12	C11	C10	X	X	X	B15	B14	<b>B</b> 1 <sub>3</sub>	B12	B11	B10
16bits	Pseudo 262k format 2	2nd	X	X	A14	A13	A12	A11	A10	X	X	X	C24	C23	C22	C21	C20	X
	202k folliat 2	3rd	X	X	B25	B24	B23	B22	B21	B20	X	X	A24	A23	A22	A21	A20	X

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# 6.6 SEG/COM Driving block

This block is used to derive the incoming power sources into the different levels of internal use voltage and current.

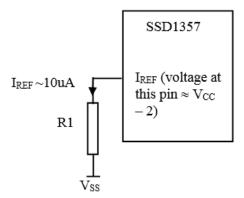
- V<sub>CC</sub> is the most positive voltage supply.
- V<sub>COMH</sub> is the Common deselected level. It is internally regulated.
- V<sub>LSS</sub> is the ground path of the analog and panel current.
- I<sub>REF</sub> is a reference current source for segment current drivers I<sub>SEG</sub>. The relationship between reference current and segment current of a color is:

$$I_{SEG} = Contrast / 8 \times I_{REF}$$

in which the contrast (1~255) is set by Set Contrast command C1h

When external  $I_{REF}$  is used, the magnitude of  $I_{REF}$  is controlled by the value of resistor, which is connected between  $I_{REF}$  pin and  $V_{SS}$  as shown in Figure 6-12. It is recommended to set  $I_{REF}$  to  $10 \pm 2uA$  so as to achieve  $I_{SEG} = 320uA$  at maximum contrast 255.

Figure 6-12: IREF Current Setting by Resistor Value



Since the voltage at  $I_{REF}$  pin is  $V_{CC} - 3V$ , the value of resistor R1 can be found as below:

For 
$$I_{REF} = 10uA$$
,  $V_{CC} = 12V$ :

$$\begin{split} R1 &= (Voltage~at~I_{REF} - V_{SS}) ~/~I_{REF} \\ &\approx (12-2) ~/~10uA \\ &= 1M\Omega \end{split}$$

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#### 6.7 SEG / COM Drivers

Segment drivers consist of 384 (128 x 3 colors) current sources to drive OLED panel. The driving current can be adjusted from 0 to 320uA with 256 steps by contrast setting command (C1h). Common drivers generate scanning voltage pulse. The block diagrams and waveforms of the segment and common driver are shown as follow.

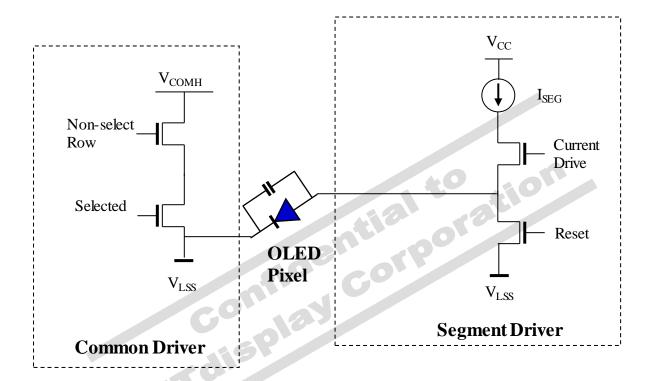


Figure 6-13: Segment and Common Driver Block Diagram

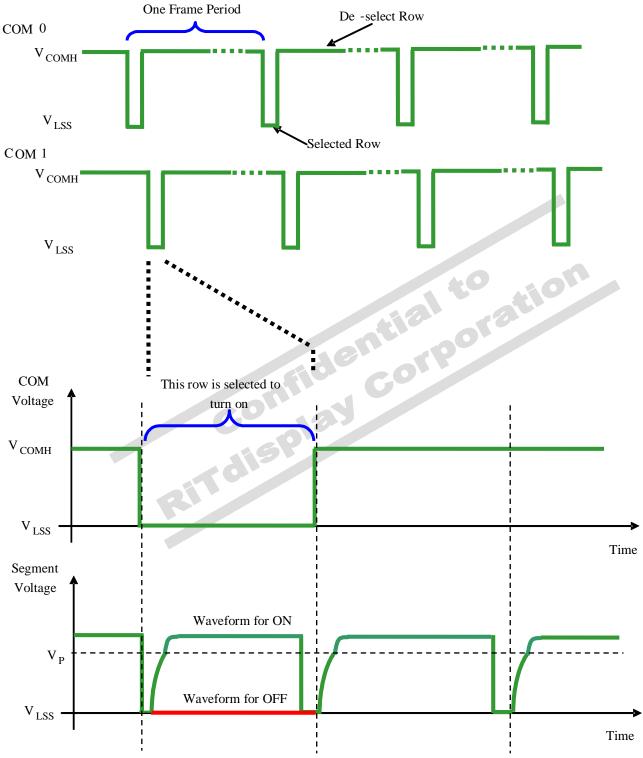
The commons are scanned sequentially, row by row. If a row is not selected, all the pixels on the row are in reverse bias by driving those commons to voltage  $V_{\text{COMH}}$  as shown in Figure 6-14.

In the scanned row, the pixels on the row will be turned ON or OFF by sending the corresponding data signal to the segment pins. If the pixel is turned OFF, the segment current is disabled and the Reset switch is enabled. On the other hand, the segment drives to I<sub>SEG</sub> when the pixel is turned ON.

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One Frame Period

Figure 6-14: Segment and Common Driver Signal Waveform



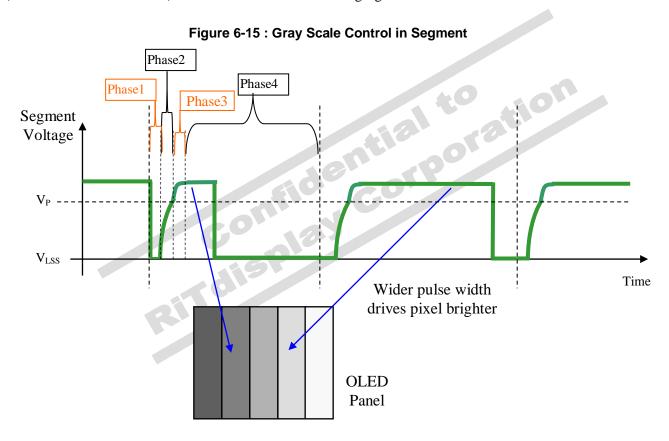
There are four phases to driving an OLED a pixel. In phase 1, the pixel is reset by the segment driver to  $V_{LSS}$  in order to discharge the previous data charge stored in the parasitic capacitance along the segment electrode. The period of phase 1 can be programmed by command B1h A[3:0]. An OLED panel with larger capacitance requires a longer period for discharging.

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In phase 2, first pre-charge is performed. The pixel is driven to attain the corresponding voltage level  $V_P$  from  $V_{LSS}$ . The amplitude of  $V_P$  can be programmed by the command BBh. The period of phase 2 can be programmed by command B1h A[7:4]. If the capacitance value of the pixel of OLED panel is larger, a longer period is required to charge up the capacitor to reach the desired voltage.

In phase 3, the OLED pixel is driven to the targeted driving voltage through second pre-charge. The second pre-charge can control the speed of the charging process. The period of phase 3 can be programmed by command B6h.

Last phase (phase 4) is current drive stage. The current source in the segment driver delivers constant current to the pixel. The driver IC employs PWM (Pulse Width Modulation) method to control the gray scale of each pixel individually. The gray scale can be programmed into different Gamma settings by command B8h, BCh, BDh / B9h. The bigger gamma setting in the current drive stage results in brighter pixels and vice versa (Details refer to Section 6.8). This is shown in the following figure.



After finishing phase 4, the driver IC will go back to phase 1 to display the next row image data. This four-step cycle is run continuously to refresh image display on OLED panel.

The length of phase 4 is defined by command B8h "Master Look Up Table for Gray Scale Pulse width (Color A,B,C)" or B9h "Use Built-in Linear LUT" or Individual Look Up Table for Gray Scale Pulse width (Color A/B/C) BCh, B8h, BDh. In the table, the gray scale is defined in incremental way, with reference to the length of previous table entry.

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#### 6.8 Gray Scale Decoder

The gray scale effect is generated by controlling the pulse width of segment drivers in current drive phase. The gray scale tables store the corresponding pulse widths of the 31 gray scale levels for Color A, C and 63 gray scale levels for Color B through the software commands B8h, B9h, BCh and BDh. The wider the pulse width, the brighter the pixel will be. The maximum pulse width setting is 124 DCLKS. Colors A, B and C are using 3 individual gray scale tables.

As shown in Figure 6-16, color A, C sub-pixel RAM data has 5 bits, represent the 31 gray scale levels from GS1 to GS31. And color B sub-pixel RAM data has 6 bits, represent the 63 gray scale levels from GS1 to GS63.

	Color A, C			Color B	
RAM data	Gray Scale	Default	RAM data	Gray Scale	Default pulse width
(5 bits)		pulse width	(6 bits)		of GS[1:63] in terms
		of GS[1:31]			of DCLK
		in terms of			
		DCLK			
00001	GS1	0	000001	GS1	0
00010	GS2	4	000010	GS2	2
00011	GS3	8	000011	GS3	4
00100	GS4	12	000100	GS4	6
:				? : d	
:				:0}	:
11101	GS29	112	111101	GS61	120
11110	GS30	116	111110	GS62	122
11111	GS31	120	111111	GS63	124

Figure 6-16: Relation between GDDRAM content and gray scale table entry for three colors in 65K color mode

GS1 has only pre-charge but no current drive stage. The duration of different GS are programmable by command B8h for color B, BCh for color A, BDh for color C and the maximum pulse width setting is 124 DCLKs.

When setting the Gray Scale Table (by B8h, BCh, BDh command), the rules below must follow:

- 1) The 63 gray scale levels are entered after command B8h for color B. The 31 gray scale levels are entered after command BCh or BDh for color A, C. Note that command B8h has to be inputted before BCh and BDh command.
- 2) The gray scale is defined in incremental way, with reference to the length of previous table entry:

Setting of GS1 has to be >= 0Setting of GS2 has to be > Setting of GS1 Setting of GS3 has to be > Setting of GS2

:
Setting of GS63 has to be > Setting of GS62

Figure 6-17: Illustration of relation between graphic display RAM value and gray scale control

Gray scale table Color A,C RAM data = 00010 (GS2) Color A,C RAM data = 11111 (GS31) Color B RAM data = 000011 (GS3) Gray Scale Value/DCLK Color B RAM data = 111101 (GS61) pulse width = 4 DCLKsA,C A,CВ В Segment pulse width = 120 DCLKs GS1 GS1 0 Voltage 4 0 GS2 GS2 4 2 GS3 GS3 8 4 Vр GS29 **GS61** 112 120 **GS30 GS62** 116 122  $V_{LSS}$ GS31 GS63 120 124 Time

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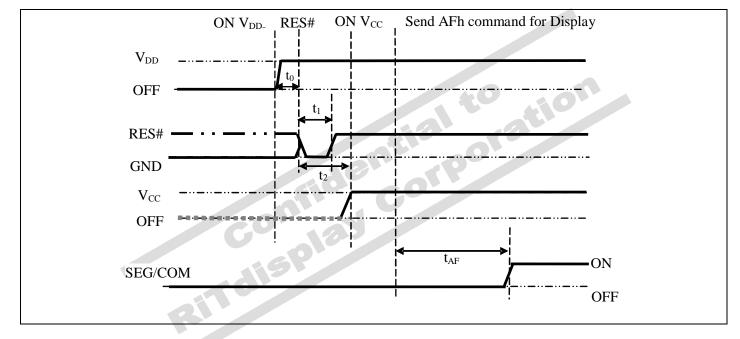
# Power ON and OFF sequence

The following figures illustrate the recommended power ON and power OFF sequence of SSD1357.

#### Power ON sequence:

- 1. Power ON V<sub>DD</sub>
- 2. After V<sub>DD</sub> become stable, wait at least 20ms (t<sub>0</sub>), set RES# pin LOW (logic low) for at least 3us (t<sub>1</sub>) (4) and then HIGH (logic high).
- 3. After set RES# pin LOW (logic low), wait for at least 3us ( $t_2$ ). Then Power ON  $V_{CC}$ <sup>(1)</sup>
- 4. After V<sub>CC</sub> become stable, send command AFh for display ON. SEG/COM will be ON after 200ms  $(t_{AF}).$
- 5. After  $V_{DD}$  become stable, wait for at least 300ms to send command.

Figure 6-18: The Power ON sequence



# Power OFF sequence:

- 1. Send command AEh for display OFF. 2. Power OFF  $V_{CC.}^{(1),(2)}$
- 3. Power OFF V<sub>DD</sub> after t<sub>OFF</sub>. (4) (where Minimum t<sub>OFF</sub>=0ms, typical t<sub>OFF</sub>=100ms)

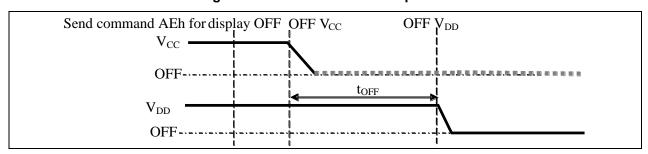


Figure 6-19: The Power OFF sequence

(1) V<sub>CC</sub> should be kept float (i.e. disable) when it is OFF.

(2) Power Pins (V<sub>DD</sub>, V<sub>CC</sub>) can never be pulled to ground under any circumstance.

 $^{(3)}$  The register values are reset after  $t_1$ .

 $^{(4)}$   $V_{DD}$  should not be Power OFF before  $V_{CC}$  Power OFF.

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#### 7 **MAXIMUM RATINGS**

Table 7-1: Maximum Ratings

(Voltage Reference to V<sub>SS</sub>)

Symbol	Parameter	Value	Unit
$V_{CC}$	Supply Voltage	-0.5 to 19.0	V
$V_{ m DD}$	Supply Voltage	-0.3 to 4.0	V
$V_{SEG}$	SEG output voltage	0 to V <sub>CC</sub>	V
$V_{COM}$	COM output voltage	0 to 0.9*V <sub>CC</sub>	V
$V_{in}$	Input voltage	Vss-0.3 to $V_{DD}$ +0.3	V
T <sub>A</sub>	Operating Temperature	-40 to +85	$^{\circ}$
$T_{stg}$	Storage Temperature Range	-65 to +150	$^{\circ}$

<sup>\*</sup>Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the limits in the Electrical Characteristics tables or Pin Description.

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aring normal operation. This \*This device may be light sensitive. Caution should be taken to avoid exposure of this device to any light source during normal operation. This device is not radiation protected.

# 8 DC CHARACTERISTICS

Conditions (Unless otherwise specified): Voltage referenced to  $V_{SS}$   $V_{DD}=1.65 \ to \ 3.5 V$   $T_A=25 ^{\circ} C$ 

Table 8-1: DC Characteristics

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
$V_{CC}$	Operating Voltage	-	8	-	18	V
$V_{\mathrm{DD}}$	Low voltage power supply, power Supply for I/O pins	-	1.65	-	3.5	V
V <sub>OH</sub>	High Logic Output Level	Iout = 100uA	$0.9*V_{DD}$	-	$V_{\mathrm{DD}}$	V
$V_{OL}$	Low Logic Output Level	Iout = 100uA	0	-	$0.1*V_{DD}$	V
$V_{\mathrm{IH}}$	High Logic Input Level	-	$0.8*V_{DD}$	-	$V_{DD}$	V
$V_{\rm IL}$	Low Logic Input Level	-	0	-	$0.2*V_{DD}$	V
I <sub>SLP_VDD</sub>	V <sub>DD</sub> Sleep mode Current	$V_{DD} = 2.8V$ , $V_{CC} = 16V$ Display OFF, No panel attached	-	-	10	uA
I <sub>SLP_VCC</sub>	V <sub>CC</sub> Sleep mode Current	V <sub>DD</sub> = 2.8V, V <sub>CC</sub> = 16V, Display OFF, No panel attached	-	-	10	uA
$I_{DD}$	V <sub>DD</sub> Supply Current	V <sub>DD</sub> = 2.8V, V <sub>CC</sub> = 16V, Display ON, No panel attached, contrast = FFh	40	720	800	uA
Icc	V <sub>CC</sub> Supply Current	V <sub>DD</sub> = 2.8V, V <sub>CC</sub> = 16V, Display ON, No panel attached, contrast = FFh	-10	2.1	2.4	mA
	Segment Output Current	Contrast = FF		320	-	uA
I <sub>SEG</sub>	Setting	Contrast = BF	-	240	-	uA
	$V_{CC}=18V$ , $I_{REF}=10uA$	Contrast = 7F	-	160	-	uA
Dev	Segment output current uniformity	$\begin{aligned} \text{Dev} &= \left(I_{SEG} - I_{MID}\right) / I_{MID} \\ I_{MID} &= \left(I_{MAX} + I_{MIN}\right) / 2 \\ I_{SEG} &= \text{Segment current at contrast FF} \end{aligned}$	-3	-	3	%
Adj. Dev	Adjacent pin output current uniformity (contrast setting = FFh)	Adj Dev = $(I[n]-I[n+1])/(I[n]+I[n+1])$	-2	-	2	%

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# **AC CHARACTERISTICS**

# Conditions (Unless otherwise specified):

Voltage referenced to V<sub>SS</sub>  $T_A = 25$ °C

Table 9-1: AC Characteristics

Symbol	Parameter	<b>Test Condition</b>	Min	Тур	Max	Unit
Fosc (1)	Oscillation Frequency of Display Timing Generator	$V_{DD} = 2.8V$	2.1	2.3	2.5	MHz
Ffrm	Frame Frequency for 128 MUX Mode	128x128 Graphic Display Mode, Display ON, Internal Oscillator Enabled	-	Fosc * 1/(D*K*128)	-	Hz
$t_{RES}$	Reset low pulse width (RES#)	-	3	-	-	us
in defaul	tands for the frequency value of t value, and B3h A[3:0] is in [0 ide ratio set by command B3h A se 1 period +Phase 2 period +	The internal oscillator and the value is 001].  A[3:0]  X	s measi	ared when command	l B3h	A[7:4] i
	LKs in current drive period		3	40		
	Ri	The internal oscillator and the value is 001].  A[3:0]  X				

#### Note

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Table 9-2: 6800-Series MCU Parallel Interface Timing Characteristics

 $(V_{DD}-V_{SS}=1.65V \text{ to } 3.5V, T_A=25^{\circ}C)$ 

Symbol	Parameter	Min	Тур	Max	Unit
$t_{\text{CYCLE}}$	Clock Cycle Time (write)	300	-	-	ns
$t_{AS}$	Address Setup Time	24	-	-	ns
t <sub>AH</sub>	Address Hold Time	0	-	-	ns
$t_{ m DSW}$	Write Data Setup Time	40	-	-	ns
$t_{\mathrm{DHW}}$	Write Data Hold Time	7	-	-	ns
t <sub>DHR</sub>	Read Data Hold Time	20	-	-	ns
t <sub>OH</sub>	Output Disable Time	_	-	70	ns
t <sub>ACC</sub>	Access Time	-	-	140	ns
PW <sub>CSL</sub>	Chip Select Low Pulse Width (read) Chip Select Low Pulse Width (write)	120 60	-	-	ns
$PW_{CSH}$	Chip Select High Pulse Width (read) Chip Select High Pulse Width (write)	60 60	-		ns
$t_R$	Rise Time	2	4	15	ns
$t_{\mathrm{F}}$	Fall Time		<u> </u>	15	ns

D/C#  $\boldsymbol{t}_{AS}$  $t_{AH}$ R/W# E  $t_{CYCLE}$  $\overline{PW}_{\underline{CSH}}$ PW<sub>CSL</sub> CS# t<sub>DHW</sub>  $t_F$  $t_{\rm DSW}$ D[15:0] (1) Valid Data (WRITE)  $\overline{t_{ACC}}$  $t_{DHR}$ D[15:0](1) (READ)-Valid Data

Figure 9-1: 6800-series MCU parallel interface characteristics

#### Note

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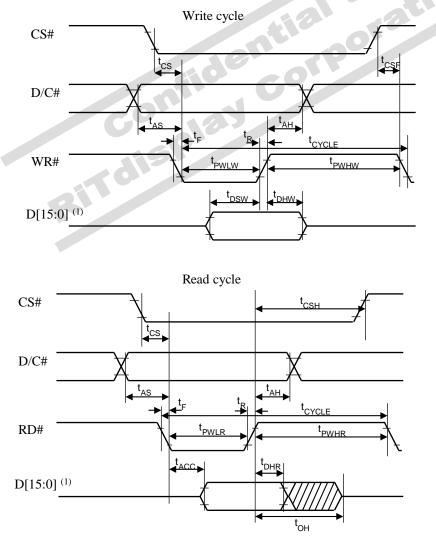
<sup>(1)</sup> when 8 bit used: D[7:0] instead; when 16 bit used: D[15:0] instead.

Table 9-3: 8080-Series MCU Parallel Interface Timing Characteristics

 $(V_{DD}-V_{SS}=1.65V \text{ to } 3.5V,\, T_A=25\,^{\circ}C)$ 

Symbol	Parameter	Min	Тур	Max	Unit
tcycle	Clock Cycle Time (write)	300	-	-	ns
tas	Address Setup Time	10	-	-	ns
tah	Address Hold Time	0	-	-	ns
$t_{DSW}$	Write Data Setup Time	40	-	-	ns
$t_{ m DHW}$	Write Data Hold Time	7	-	-	ns
t <sub>DHR</sub>	Read Data Hold Time	20	-	-	ns
tон	Output Disable Time	-	-	46	ns
tacc	Access Time	-	-	140	ns
tpwlr	Read Low Time	150	-	-	ns
tpwlw	Write Low Time	60	-	-	ns
tpwhr	Read High Time	60	-	-	ns
tpwhw	Write High Time	60	-	-	ns
$t_R$	Rise Time	-	-	15	ns
$t_{\rm F}$	Fall Time	-	-	15	ns
tcs	Chip select setup time	0	-		ns
tcsh	Chip select hold time to read signal	0		-	ns
t <sub>CSF</sub>	Chip select hold time	20	-	-	ns

Figure 9-2: 8080-series MCU parallel interface characteristics



#### Note

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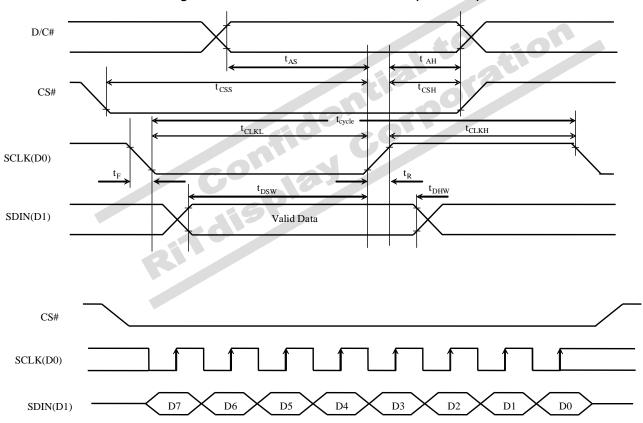
<sup>(1)</sup> when 8 bit used: D[7:0] instead; when 16 bit used: [15:0] instead.

Table 9-4 : Serial Interface Timing Characteristics (4-wire SPI)

 $(V_{DD}-V_{SS}=1.65V \text{ to } 3.5V,\, T_A=25^{\circ}C)$ 

Symbol	Parameter	Min	Тур	Max	Unit
t <sub>cycle</sub>	Clock Cycle Time	100	-	-	ns
$t_{AS}$	Address Setup Time	15	-	-	ns
$t_{AH}$	Address Hold Time	42	-	-	ns
t <sub>CSS</sub>	Chip Select Setup Time	20	-	-	ns
t <sub>CSH</sub>	Chip Select Hold Time	10	-	-	ns
$t_{ m DSW}$	Write Data Setup Time	15	-	-	ns
$t_{ m DHW}$	Write Data Hold Time	20	-	-	ns
$t_{CLKL}$	Clock Low Time	20	-	-	ns
t <sub>CLKH</sub>	Clock High Time	20	-	-	ns
$t_R$	Rise Time	-	-	15	ns
$t_{\mathrm{F}}$	Fall Time	-	_	15	ns

Figure 9-3 : Serial interface characteristics (4-wire SPI)



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Table 9-5: Serial Interface Timing Characteristics (3-wire SPI)

 $(V_{DD}-V_{SS}=1.65V \text{ to } 3.5V,\, T_A=25^{\circ}C)$ 

Symbol	Parameter	Min	Тур	Max	Uni
					t
t <sub>cycle</sub>	Clock Cycle Time	100	-	-	ns
t <sub>CSS</sub>	Chip Select Setup Time	20	-	-	ns
$t_{CSH}$	Chip Select Hold Time	44	-	-	ns
$t_{DSW}$	Write Data Setup Time	15	-	-	ns
$t_{DHW}$	Write Data Hold Time	20	-	-	ns
$t_{CLKL}$	Clock Low Time	20	-	-	ns
$t_{CLKH}$	Clock High Time	20	-	-	ns
$t_R$	Rise Time	-	-	15	ns
$t_{\rm F}$	Fall Time	-	-	15	ns

Figure 9-4 : Serial interface characteristics (3-wire SPI) CS# SCLK SDIN D/C# D7 D6 D5 D3 D2 D1 D0  $t_{CSH}$ CS#  $t_{CYCLE}$  $t_{CLKH}$ t<sub>CLKL</sub> SCLK (D0) $\xrightarrow{t_F}$  $t_{DSW}$  $t_{\,\mathrm{DHW}}$ SDIN Valid Data (D1)

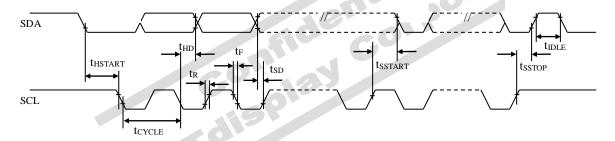
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Table 9-6: I<sup>2</sup>C Interface Timing Characteristics

 $(V_{DD}$ -  $V_{SS}$  =1.65V to 3.5V,  $T_A$  = 25°C)

Symbol	Parameter	Min	Тур	Max	Unit
$t_{ m cycle}$	Clock Cycle Time	2.5	-	-	us
t <sub>HSTART</sub>	Start condition Hold Time	0.6	-	-	us
t <sub>HD</sub>	Data Hold Time (for "SDA <sub>OUT</sub> " pin)	0	-	-	ns
	Data Hold Time (for "SDA <sub>IN</sub> " pin)	300	-	-	ns
$t_{\mathrm{SD}}$	Data Setup Time	100	-	-	ns
t <sub>SSTART</sub>	Start condition Setup Time (Only relevant for a repeated Start condition)	0.6	-	-	us
t <sub>SSTOP</sub>	Stop condition Setup Time	0.6	-	-	us
$t_R$	Rise Time for data and clock pin	-	-	300	ns
$t_{\mathrm{F}}$	Fall Time for data and clock pin	-	-	300	ns
t <sub>IDLE</sub>	Idle Time before a new transmission can start	1.3	-	-	us

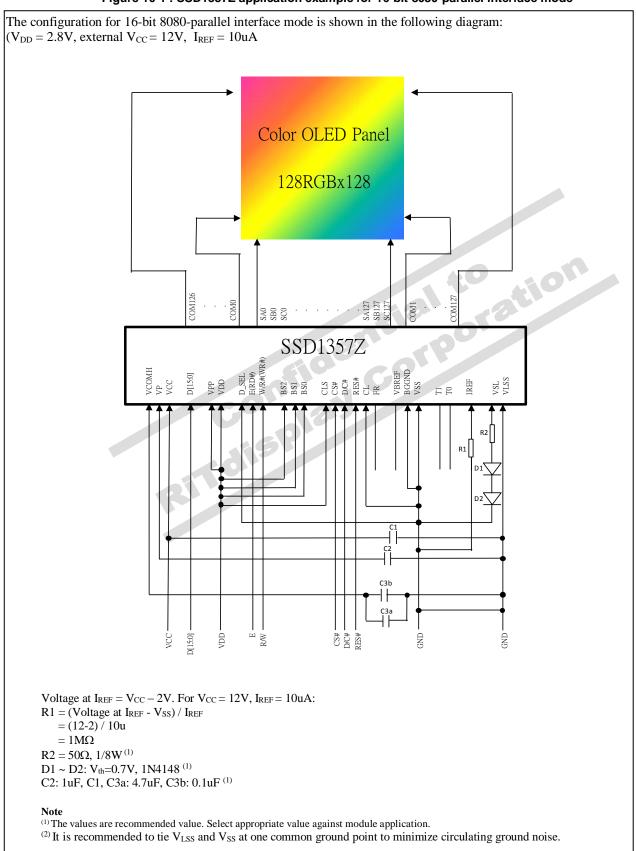
Figure 9-5 : I<sup>2</sup>C interface Timing characteristics



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# 10 APPLICATION EXAMPLE

Figure 10-1: SSD1357Z application example for 16-bit 8080-parallel interface mode



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The product(s) listed in this datasheet comply with Directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment and People's Republic of China Electronic Industry Standard SJ/T 11363-2006 "Requirements for concentration limits for certain hazardous substances in electronic information products (电子信息产品中有毒有害物质的限量要求)". Hazardous Substances test report is available upon request.

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# **Appendix : SSD1357 Command Table and Command Description**

# 1 COMMAND TABLE

# Table 1-1: SSD1357 Command Table

(D/C# = 0, R/W#(WR#) = 0, E(RD#) = 1) unless specific setting is stated Single byte command (D/C# = 0), Multiple byte command (D/C# = 0) for first byte, D/C# = 1 for other bytes)

	Single byte command (D/C# = 0), Multiple byte command (D/C# = 0 for first byte, D/C# = 1 for other bytes)  Sundamental Command Table  D/C#   Hex   D7   D6   D5   D4   D3   D2   D1   D0   Command   Description													
D/C#	Hex	<b>D7</b>	<b>D6</b>	<b>D5</b>	<b>D4</b>	<b>D3</b>	D2	<b>D</b> 1	<b>D</b> 0	Command	Description			
0 1 1	15 A[6:0] B[6:0]	0 *	0 A <sub>6</sub> B <sub>6</sub>	0 A <sub>5</sub> B <sub>5</sub>	1 A <sub>4</sub> B <sub>4</sub>	0 A <sub>3</sub> B <sub>3</sub>	1 A <sub>2</sub> B <sub>2</sub>	0 A <sub>1</sub> B <sub>1</sub>	1 A <sub>0</sub> B <sub>0</sub>	Set Column Address	A[6:0]: Start Address. [reset=0] B[6:0]: End Address. [reset=127] Range from 0 to 127			
0 1 1	75 A[6:0] B[6:0]	0 *	1 A <sub>6</sub> B <sub>6</sub>	1 A <sub>5</sub> B <sub>5</sub>	1 A <sub>4</sub> B <sub>4</sub>	0 A <sub>3</sub> B <sub>3</sub>	1 A <sub>2</sub> B <sub>2</sub>	0 A <sub>1</sub> B <sub>1</sub>	1 A <sub>0</sub> B <sub>0</sub>	Set Row Address	A[6:0]: Start Address. [reset=0] B[6:0]: End Address. [reset=127] Range from 0 to 127			
0	5C	0	1	0	1	1	1	0	0	Write RAM Command	Enable MCU to write Data into RAM  Enable MCU to read Data from RAM			
0	5D	0	1	0	1	1	1	0	1	Read RAM Command	400			
0 1 1 1	A0 A[7:0] B[7:0]	1 A <sub>7</sub> 0	0 A <sub>6</sub> 0	1 As 0	0 A <sub>4</sub> 0	0 A <sub>3</sub> 0	0 A <sub>2</sub> 0	0 A <sub>1</sub> 0	0 A <sub>0</sub> 0	Set Re-map / Color Depth (Display RAM to Panel)	A[0]=0b, Horizontal address increment [reset] A[0]=1b, Vertical address increment A[1]=0b, Column address 0 is mapped to SEG0 [reset] A[1]=1b, Column address 127 is mapped to SEG0  A[2]=0b, Color sequence: A → B → C [reset] A[2]=1b, Color sequence is swapped: C → B → A  A[3]=0b, Reserved [reset] A[3]=1b, Reserved  A[4]=0b, Scan from COM0 to COM[N-1] [reset] A[4]=1b, Scan from COM[N-1] to COM0. Where N is the Multiplex ratio.  A[5]=0b, Disable COM Split Odd Even A[5]=1b, Enable COM Split Odd Even [reset]  A[7:6] Set Color Depth, 00b: 256color 01b: 65k color [reset] 10b: 262k color 11b Pseudo 262k color, 16-bit format 2  Refer to Product Preview Table 6-6 for details			

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Funda	undamental Command Table  D/C#   Hex   D7   D6   D5   D4   D3   D2   D1   D0   Command   Description														
D/C#	Hex	<b>D7</b>	<b>D6</b>	<b>D5</b>	<b>D4</b>	<b>D3</b>	<b>D2</b>	D1	<b>D</b> 0	Command	Description				
0	A1 A[6:0]	1 *	0 A <sub>6</sub>	1 A <sub>5</sub>	0 A <sub>4</sub>	0 A <sub>3</sub>	0 A <sub>2</sub>	0 A <sub>1</sub>	1 A <sub>0</sub>	Set Display Start Line	Set vertical scroll by RAM from 0~127. [reset=00h]				
0	A2 A[6:0]	1 *	0 A <sub>6</sub>	1 A <sub>5</sub>	0 A <sub>4</sub>	0 A <sub>3</sub>	0 A <sub>2</sub>	1 A <sub>1</sub>	0 A <sub>0</sub>	Set Display Offset	Set vertical scroll by Row from 0-127. [reset=00h]				
0	A4~A7	1	0	1	0	0	1	$X_1$	X <sub>0</sub>	Set Display Mode	A4h: All OFF  A5h: All ON (All pixels have GS63)  A6h: Reset to normal display [reset]  A7h: Inverse Display (GS0 -> GS63, GS1 -> GS62,)				
0	AE~AF	1	0	1	0	1	1	1	<b>X</b> <sub>0</sub>	Set Sleep mode ON/OFF	AEh = Sleep mode On (Display OFF) AFh = Sleep mode OFF (Display ON)				
0 1	B1 A[7:0]	1 A <sub>7</sub>	0 A <sub>6</sub>	1 As	1 A <sub>4</sub>	0 A <sub>3</sub>	0 A <sub>2</sub>	0 A <sub>1</sub>	1 A <sub>0</sub>	Set Reset (Phase 1) / Pre-charge (Phase 2) period	A[3:0] Phase 1 period of 2~30 DCLK(s) clocks [reset=0100b] A[3:0]: 0 invalid 1 = 2 DCLKs 2 = 4 DCLKs : 15 = 30DCLKs  A[7:4] Phase 2 period of 2~30 DCLK(s) clocks [reset=1000b] A[7:4]: 0 invalid 1 = 2 DCLKs 2 = 4 DCLKs : 15 = 30DCLKs  Note  (1) 0 DCLK is invalid in phase 1 & phase 2				

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Funda	mental (	Com	man	d Ta	ble						
<b>D</b> /C#	Hex	<b>D7</b>	<b>D6</b>	<b>D5</b>	<b>D4</b>	<b>D3</b>	D2	D1	<b>D</b> 0	Command	Description
0 1	B3 A[7:0]	1 A <sub>7</sub>	0 A <sub>6</sub>	1 A <sub>5</sub>	1 A <sub>4</sub>	0 A <sub>3</sub>	0 A <sub>2</sub>	1 A <sub>1</sub>	1 A <sub>0</sub>	Front Clock Divider (DivSet)/ Oscillator Frequency	A[3:0]   DIVSET
0 1	B6 A[3:0]	1 0	0 0	1 0	1 0	0 A <sub>3</sub>	1 A <sub>2</sub>	0 A <sub>1</sub>	0 A <sub>0</sub>	Set Second Pre- charge Period	A[3:0] Set Second Pre-charge Period  0000b invalid 0001b 1 DCLKS 0010b 2 DCLKS 1000 8 DCLKS [reset] 1111 15 DCLKS
O 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	B8 A1[7:0] A2[7:0] A62[7:0] A63[7:0]	A2 <sub>7</sub>	A2 <sub>6</sub>	A2 <sub>5</sub>	A2 <sub>4</sub>	A1 <sub>3</sub> A2 <sub>3</sub>	A2 <sub>2</sub>	A2 <sub>1</sub>	A2 <sub>0</sub>		The next 63 data bytes define Gray Scale (GS) Table by setting the gray scale pulse width in unit of DCLK's (ranges from 0d ~ 180d).  A1[7:0]: Gamma Setting for GS1, A2[7:0]: Gamma Setting for GS2, : A62[7:0]: Gamma Setting for GS62, A63[7:0]: Gamma Setting for GS63  Note  (1] 0 ≤ Setting of GS1 < Setting of GS2 < Setting of GS3 < Setting of GS62 < Setting of GS63  (2) GS0 does not has pre-charge and current drive stages. (3) GS1 can be set as only pre-charge but no current drive stage by input gamma setting for GS1 equals 0.  (4) When command B8h is input only, color A, B, C will follow the master LUT. (5) When command BCh is input, it selects individual LUT for color A, GS1~31A; When command BDh is input, it selects individual LUT for color C, GS1~31C  (6) To select individual LUT for color B, A and C, command B8h should be input before command BCh and BDh,

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<b>D/C</b> #	Hex	D7	D6	D5	<b>D4</b>	D3	<b>D2</b>	<b>D1</b>	$\mathbf{D0}$	Command	Description	
0	B9	1	0	1	1	1	0	0	1	Communa	Reset to default Look Up Table:	
Ü	D,	1		1	•	•		Ů	•		r	
											Color A Color B Color C	
										Use Built-in	GS1A = 0 DCLK GS1B = 0 DCLK GS1C = 0 DCLK	
										Linear LUT	GS2A = 4 DCLK	
										[reset= linear]		
											GS31A = 120 DCLK	
0	BB	1	0	1	1	1	0	1	1		Set pre-charge voltage level.[reset = 11110b]	
1	A[4:0]	0	0	0	$A_4$	$A_3$	$A_2$	$A_1$	$A_0$			
											A[4:0]   Hex code   pre-charge voltage	
											00000 00h 0.10 x V <sub>CC</sub>	
										Set Pre-charge	11110 1Eh 0.50 x V <sub>CC</sub> [reset]	
										voltage	11111 1Fh 0.5133 x V <sub>CC</sub>	
											Note (1)Pre-charge voltage level must be smaller than COM	
											deselect voltage level	
											descreet voltage level	
0	BC	1	0	1	1	1	1	0	0		The next 31 data bytes define Gray Scale (GS) Table by	
1	A1[7:0]	A17	A16	A15	A14	A13	$A1_2$	A11	A10		setting the gray scale pulse width in unit of DCLK's	
1							$A2_2$				(ranges from 0d ~ 180d) for color A.	
1	112[,.0]	112/	1120	1123	1124	1123	1122	7121	1120	10	A1[7-0], C S S C C C	
_	•				•					0	A1[7:0]: Gamma Setting for GS1A, A2[7:0]: Gamma Setting for GS2A,	
1	•	•	•	•					11		AZ[7.0]. Gamina Setting for GSZA,	
1											A62[7:0]: Gamma Setting for GS30A,	
1	A30[7:0]	A30 <sub>7</sub>	$A30_{6}$	A30 <sub>5</sub>	A30 <sub>4</sub>	$A30_3$	$A30_2$	A30 <sub>1</sub>	$A30_0$	Individual Leaf-	A (217.01. Campa Catting for CC21 A	
1	A31[7:0]	A31 <sub>7</sub>	A31 <sub>6</sub>	A31 <sub>5</sub>	A31 <sub>4</sub>	A31 <sub>3</sub>	A31 <sub>2</sub>	A31 <sub>1</sub>	A31 <sub>0</sub>	Individual Look Up Table for		
										Gray Scale	Note	
										Pulse width	$(1)$ 0 $\leq$ Setting of GS1 $<$ Setting of GS2 $<$ Setting of GS3	
										(Color A)	< Setting of GS30 < Setting of GS31	
			1								(2) GS0 does not has pre-charge and current drive stages. (3) GS1 can be set as only pre-charge but no current drive	
											stage by input gamma setting for GS1 equals 0.	
											(4) When command B8h is input, it selects one LUT for col	
											A, B and C. i.e. GS1~31A, GS1~63B and GS1~31C are	
											updated.	
											(5) Command B8h should be input before command BCh at	
											BDh to select individual LUT for color B, A and C.	
		l	l	l	l							

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Funda	mental (	Com	man	d Ta	ble						
D/C#	Hex	<b>D7</b>	<b>D6</b>	<b>D5</b>	D4	D3	<b>D2</b>	D1	<b>D</b> 0	Command	Description
0 1 1 1 1 1 1 1 1 1	A2[7:0]	A2 <sub>7</sub>	A2 <sub>6</sub>	A2 <sub>5</sub>	A2 <sub>4</sub>		A2 <sub>2</sub>	A2 <sub>1</sub>	A2 <sub>0</sub>	Individual Look Up Table for Gray Scale Pulse width (Color C)	The next 31 data bytes define Gray Scale (GS) Table by setting the gray scale pulse width in unit of DCLK's (ranges from 0d ~ 180d) for color C.  A1[7:0]: Gamma Setting for GS1C, A2[7:0]: Gamma Setting for GS2C, : A62[7:0]: Gamma Setting for GS30C, A63[7:0]: Gamma Setting for GS31C  Note  (1) 0 \leq Setting of GS1 \leq Setting of GS31  (2) GS0 does not has pre-charge and current drive stages. (3) GS1 can be set as only pre-charge but no current drive stage by input gamma setting for GS1 equals 0. (4) When command B8h is input, it selects one LUT for color A, B and C. i.e. GS1~31A, GS1~63B and GS1~31C are updated. (5) Command B8h should be input before command BCh and BDh to select individual LUT for color B, A and C.
0 1	BE A[2:0]	1 0	0 0	1 0	1 0	1 0	1 A <sub>2</sub>	1 A <sub>1</sub>	0 A <sub>0</sub>	Set V <sub>COMH</sub> Voltage	A[2:0]   Hex code   V COMH   O00   O0h   0.72 x V CC   COME   C
0 1 1 1	C1 A[7:0] B[7:0] C[7:0]	1 A <sub>7</sub> B <sub>7</sub> C <sub>7</sub>	$B_6$	B <sub>5</sub>	$B_4$	$\mathbf{B}_3$	$0 \\ A_2 \\ B_2 \\ C_2$	$\begin{matrix} 0 \\ A_1 \\ B_1 \\ C_1 \end{matrix}$	1 A <sub>0</sub> B <sub>0</sub> C <sub>0</sub>	Set Contrast Current for Color A,B,C	A[7:0] Contrast Value Color A [reset=7Fh] B[7:0] Contrast Value Color B [reset=7Fh] C[7:0] Contrast Value Color C [reset=7Fh]
0 1	C7 A[3:0]	1 *	1 *	0 *	0 *	0 A <sub>3</sub>	1 A <sub>2</sub>	1 A <sub>1</sub>	1 A <sub>0</sub>	Master Contrast Current Control	A[3:0]: 0000b reduce output currents for all colors to 1/16 0001b reduce output currents for all colors to 2/16 1110b reduce output currents for all colors to 15/16 1111b no change [reset]
0	CA A[6:0]	1 0	1 A <sub>6</sub>	0 A <sub>5</sub>	0 A <sub>4</sub>	1 A <sub>3</sub>	0 A <sub>2</sub>	1 A <sub>1</sub>	0 A <sub>0</sub>	Set MUX Ratio	A[6:0] MUX ratio 4MUX ~ 128MUX, [reset=127], (Range from 3 to 127)
0	E3	1	1	1	0	0	0	1	1	NOP	Command for No Operation

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Funda	andamental Command Table														
<b>D/C</b> #	Hex	<b>D7</b>	<b>D6</b>	<b>D5</b>	<b>D4</b>	<b>D3</b>	D2	D1	<b>D</b> 0	Command	Description				
0	FD	1	1	1	1	1	1	0	1		A[7:0]: MCU protection status [reset = 12h]				
1	A[7:0]	A <sub>7</sub>	$A_6$	$A_5$	$A_4$	$A_3$	$A_2$	$A_1$	$A_0$		A[7:0] = 12h, Unlock OLED driver IC MCU interface from entering command [reset]				
											A[7:0] = 16h, Lock OLED driver IC MCU interface from				
										Set Command	entering command				
										Lock					
											Note				
											(1) The locked OLED driver IC MCU interface prohibits all				
											commands and memory access except the FDh command.				

#### Note

Gonfidential to ation confidential corporation at the confidential to ation (1) "\*" stands for "Don't care".

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Table 1-2: SSD1357 Graphic Acceleration Command List

Set (GAC) (D/C# = 0, R/W#(WR#)= 0, E(RD#) = 1) unless specific setting is stated Single byte command (D/C# = 0), Multiple byte command (D/C# = 0 for first byte, D/C# = 1 for other bytes)

Grap	hic acc	eler	atior	ı con	nma	nd					
<b>D</b> /C#	Hex	<b>D7</b>	<b>D6</b>	<b>D5</b>	<b>D4</b>	<b>D3</b>	D2	D2	<b>D</b> 0	Command	Description
0	96	1	0	0	1	0	1	1	0		A[7:0] = 00000000b No scrolling
1	A[7:0]	$A_7$	$A_6$	$A_5$	$A_4$	$A_3$	$A_2$	$A_1$	$A_0$		A[7:0] = 00000001b to 00111111b Scroll towards SEG127 with 1 column offset
1	B[6:0]	0	$B_6$	$B_5$	$B_4$	$\mathbf{B}_3$	$\mathbf{B}_2$	$\mathbf{B}_1$	$B_0$		A[7:0] = 01000000b to 11111111b
1	C[7:0]	0	$C_6$	$C_5$	$C_4$	$C_3$	$C_2$	$C_1$	$C_0$		Scroll towards SEG0 with 1 column offset
1	D[6:0]	0	$D_6$	$D_5$	$D_4$	$D_3$	$D_2$	$D_1$	$D_0$		75.60
1	E[1:0]	0	0	0	0	0	0	$E_1$	$E_0$		B[6:0]: start row address
											C[7:0]: end row address
										Horizontal Scroll	
										Tiorizontal Scroll	D[6:0]: Reserved (reset=00h)
											E[1:0]: scrolling time interval
											00b Invalid
											01b normal
											10b slow 11b slowest
											Note
										100	Operates during display ON.
	0.5		0							190	
0	9E	1	0	0	1	1	1	1	0		Stop horizontal scroll
										Stop Moving	Note
											After sending 9Eh command to stop the scrolling
											action, the ram data needs to be rewritten
0	9F	1	0	0	1	1	1	1	1	Start Moving	Start horizontal scroll

#### Note

(2) "\*" stands for "Don't care".

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#### 2 COMMAND DESCRIPTION

#### 2.1 Set Column Address (15h)

This triple byte command specifies column start address and end address of the display data RAM. This command also sets the column address pointer to column start address. This pointer is used to define the current read/write column address in graphic display data RAM. If horizontal address increment mode is enabled by command A0h, after finishing read/write one column data, it is incremented automatically to the next column address. Whenever the column address pointer finishes accessing the end column address, it is reset back to start column address and the row address is incremented to the next row.

#### 2.2 Set Row Address (75h)

This triple byte command specifies row start address and end address of the display data RAM. This command also sets the row address pointer to row start address. This pointer is used to define the current read/write row address in graphic display data RAM. If vertical address increment mode is enabled by command A0h, after finishing read/write one row data, it is incremented automatically to the next row address. Whenever the row address pointer finishes accessing the end row address, it is reset back to start row address.

For example, column start address is set to 2 and column end address is set to 125, row start address is set to 1 and row end address is set to 126. Horizontal address increment mode is enabled by command A0h. In this case, the graphic display data RAM column accessible range is from column 2 to column 125 and from row 1 to row 126 only. In addition, the column address pointer is set to 2 and row address pointer is set to 1. After finishing read/write one pixel of data, the column address is increased automatically by 1 to access the next RAM location for next read/write operation(solid line in Figure 2-1). Whenever the column address pointer finishes accessing the end column 125, it is reset back to column 2 and row address is automatically increased by 1(solid line in Figure 2-1). While the end row 126 and end column 125 RAM location is accessed, the row address is reset back to 1 and the column address is reset back to 2(dotted line in Figure 2-1).

Figure 2-1: Example of Column and Row Address Pointer Movement

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#### 2.3 Write RAM Command (5Ch)

After entering this single byte command, data entries will be written into the display RAM until another command is written. Address pointer is increased accordingly. This command must be sent before write data into RAM.

# 2.4 Read RAM Command (5Dh)

After entering this single byte command, data is read from display RAM until another command is written. Address pointer is increased accordingly. This command must be sent before read data from RAM.

### 2.5 Set Re-map & Dual COM Line Mode (A0h)

This command has multiple configurations and each bit setting is described as follows:

• Address increment mode (A[0])

When A[0] is set to 0, the driver is set as horizontal address increment mode. After the display RAM is read / written, the column address pointer is increased automatically by 1. If the column address pointer reaches column end address, the column address pointer is reset to column start address and row address pointer is increased by 1. The sequence of movement of the row and column address point for horizontal address increment mode is shown in Figure 2-2.

 Col 0
 Col 1
 .....
 Col 126
 Col 127

 Row 0
 .....
 .....
 .....
 .....

 Row 1
 .....
 .....
 .....
 .....

 Row 126
 .....
 .....
 .....
 .....

 Row 127
 .....
 .....
 .....
 .....

Figure 2-2: Address Pointer Movement of Horizontal Address Increment Mode

When A[0] is set to 1, the driver is set to vertical address increment mode. After the display RAM is read / written, the row address pointer is increased automatically by 1. If the row address pointer reaches the row end address, the row address pointer is reset to row start address and column address pointer is increased by 1. The sequence of movement of the row and column address point for vertical address increment mode is shown in Figure 2-3.

 Col 0
 Col 1
 .....
 Col 126
 Col 127

 Row 0
 .....
 .....

 Row 1
 .....
 .....

 Row 126
 .....
 .....

Figure 2-3: Address Pointer Movement of Vertical Address Increment Mode

# • Column Address Remap (A[1])

Row 127

This command bit is made for increasing the layout flexibility of segment signals in OLED module with segment arranged from left to right (when A[1] is set to 0) or vice versa (when A[1] is set to 1), as demonstrated in Figure 2-4.

A[1] = 0 (reset): RAM Column  $0 \sim 127$  maps to Col $0 \sim$ Col127

A[1] = 1: RAM Column  $0 \sim 127$  maps to Col127 $\sim$ Col0

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- Color Remap (A[2])
  - A[2] = 0 (reset): color sequence  $A \rightarrow B \rightarrow C$
  - A[2] = 1: color sequence  $C \rightarrow B \rightarrow A$
- COM scan direction Remap (A[4])

This command bit determines the scanning direction of the common for flexible layout of common signals in OLED module either from up to down or vice versa.

- A[1] = 0 (reset): Scan from up to down
- A[1] = 1: Scan from bottom to up
- Details of pin arrangement can be found in Figure 2-4.
- Odd even split of COM pins (A[5])
  - This command bit can set the odd even arrangement of COM pins.
  - A[5] = 0 (reset): Disable COM split odd even, pin assignment of common is in sequential as COM127 COM126...COM 65 COM64...SEG479...SEG0...COM0 COM1...COM62 COM63
  - A[5] = 1: Enable COM split odd even, pin assignment of common is in odd even split as COM127 COM125...COM3 COM1...SEG479...SEG0...COM0 COM2...COM124 COM126 Details of pin arrangement can be found in Figure 2-4.

Figure 2-4: COM Pins Hardware Configuration (MUX ratio: 128) A[4]=0A[3]=0Disable Odd Even Split of Disable COM Left / Right COM Scan Direction: from COM0 to COM127 COM pins Remap ROW12 ROW6 OMO COM127 COM63 Pad 1,2,3,...Gold Bumps face up A[3]=0A[4]=0A[5] = 1Enable Odd Even Split of Disable COM Left / Right COM Scan Direction: from COM pins Remap COM0 to COM127 ROW126 ROW127 128 x 128

• Display color mode (A[7:6]) Select either 262k, 65k or 256 color mode.

ROW

COM64

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SSD1357Z

COM63

COM127

Pad 1,2,3,...

COM0

Gold Bumps face up

# 2.6 Set Display Start Line (A1h)

This command is used to set Display Start Line register to determine starting address of display RAM to be displayed by selecting a value from 0 to 127. Figure 2-5 shows an example of using this command when MUX ratio = 128 and MUX ratio = 100 and Display Start Line = 28. In there, "Row" means the graphic display data RAM row.

Figure 2-5: Example of Set Display Start Line with no Remap

	128	128	100	100	MUX ratio (CAh)
COM Pin	0	28	0	28	Display start line (A1h)
COM0	Row0	Row28	Row0	Row28	
COM1	Row1	Row29	Row1	Row29	1
COM2	Row2	Row30	Row2	Row30	1
COM3	Row3	Row31	Row3	Row31	1
COM4	Row4	Row32	Row4	Row32	1
COM5	Row5	Row33	Row5	Row33	1
COM6	Row6	Row34	Row6	Row34	1
:	:	:	1:	:	1
:	:	:	:	:	1
:	:	:	:	:	1
:	1:	:	:	:	1
COM95	Row95	Row123	Row95	Row124	†
COM96	Row96	Row124	Row96	Row125	1
COM97	Row97	Row125	Row97	Row126	1
COM98	Row98	Row126	Row98	Row127	1
COM99	Row99	Row120 Row127	Row99	Row0	1
COM100	Row100	Row0	- KOW 99	- Kowo	
COM101	Row100	Row0	- 12/2/2	470	
COM101 COM102	Row101	Row2		10	-
COM102	Row102	Row2 Row3	500	-	-
COM103	Row103	Row4	. 40	-	-
COM104 COM105	Row104 Row105	Row5		-	-
COM103	Row105	Row6	20	-	-
COM100 COM107	Row100	Row7		-	-
COM107 COM108	Row107	Row8		-   -	-
COM108	Row108	Row9		-	-
COM109 COM110	Row109 Row110	Row10	-	-	-
COM110 COM111	Row110 Row111	Row10 Row11			-
COM111 COM112	Row111	Row12		-	-
COM112 COM113		Row12 Row13	-	<u> </u>	-
	Row113				-
COM114	Row114	Row14	-	-	-
COM115	Row115	Row15	-	-	-
COM116	Row116	Row16	-	-	4
COM117	Row117	Row17	-	-	4
COM118	Row118	Row18	-	-	4
COM119	Row119	Row19	-	-	4
COM120	Row120	Row20	-	-	4
COM121	Row121	Row21	-	-	4
COM122	Row122	Row22	-	-	4
COM123	Row123	Row23	-	-	4
COM124	Row124	Row24	-	-	4
COM125	Row125	Row25	-	-	4
COM126	Row126	Row26	-	-	1
COM127	Row127	Row27	-	-	
Display example	SOLOMON SYSTECH	SOLOMON SYSTECH	SOLOMON	SOLOMON SYSTECH	SOLOMON
İ	SISILUII				
	(a)	(b)	(c)	(d)	(GDDARAM)

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# 2.7 Set Display Offset (A2h)

This command specifies the mapping of display start line (it is assumed that COM0 is the display start line, display start line register equals to 0) to one of COM0-127. For example, to move the COM16 towards the COM0 direction for 16 lines, A[7:0] should be given by 00010000. The figure below shows an example of this command. In there, "Row" means the graphic display data RAM row.

Figure 2-6: Example of Set Display Offset with no Remap

	a	b	С	Case
	128	96	96	MUX ratio (CAh)
	0	0	32	Display offset (A2h A[7:0])
COM0	Row0	Row0	Row32	
COM1	Row1	Row1	Row33	1
COM2	Row2	Row2	Row34	1
:	:	:	:	
COM61	Row61	Row61	Row93	<u>]</u>
COM62	Row62	Row62	Row94	
COM63	Row63	Row63	Row95	]
COM64	Row64	Row64	-	]
COM65	Row65	Row65	-	]
COM66	Row66	Row66	-	7
:	:	:	:	1
COM93	Row93	Row93	-	
COM94	Row94	Row94	-	
COM95	Row95	Row95	-	
COM96	Row96	-	Row0	
COM97	Row97	-	Row1	40
COM98	Row98	_	Row2	
:	:	:	:	
COM125	Row125	_	Row29	
COM126		_	Row30	
COM127		-	Row31	
Display				
example				
campic			COLOMON	
	SOLOMON	COLOMON		SOLOMON
	SYSTECH			SYSTECH
	(a)	(c)	(d)	(GDDARAM)

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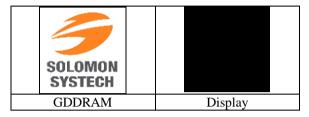
# 2.8 Set Display Mode (A4h ~ A7h)

These are single byte command and they are used to set Normal Display, Entire Display ON, Entire Display OFF and Inverse Display.

• All OFF (A4h)

Force the entire display to be at gray scale level "GS0" regardless of the contents of the display data RAM as shown in Figure 2-7.

Figure 2-7: Example of Entire Display OFF



• Set Entire Display ON (A5h)

Force the entire display to be at gray scale "GS63" regardless of the contents of the display data RAM as shown in Figure 2-8.

Figure 2-8: Example of Entire Display ON



• Set Entire Display OFF (A6h)

Reset the above effect and turn the data to ON at the corresponding gray level. Figure 2-9 shows an example of Normal Display.

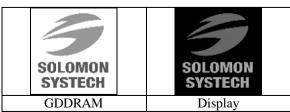
Figure 2-9: Example of Normal Display



• Inverse Display (A7h)

The gray level of display data are swapped such that "GS0"  $\leftrightarrow$  "GS63", "GS1"  $\leftrightarrow$  "GS62", ... Figure 2-10 shows an example of inverse display.

Figure 2-10: Example of Inverse Display



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### 2.9 Set Sleep mode ON/OFF (AEh / AFh)

These single byte commands are used to turn the OLED panel display ON or OFF.

When the display is OFF (command AEh), the segment is in V<sub>SS</sub> state and common is in high impedance state.

### 2.10 Set Phase Length (B1h)

This double byte command sets the length of phase 1 and 2 of segment waveform of the driver.

- Phase 1 (A[3:0]): Set the period from 2 to 30 in the unit of 2 DCLKs. A larger capacitance of the OLED pixel may require longer period to discharge the previous data charge completely.
- Phase 2 (A[7:4]): Set the period from 2 to 30 in the unit of 2DCLKs. A longer period is needed to charge up a larger capacitance of the OLED pixel to the target voltage V<sub>P</sub>.

### 2.11 Set Front Clock Divider / Oscillator Frequency (B3h)

This double byte command consists of two functions:

- Front Clock Divide Ratio (A[3:0])
   Set the divide ratio to generate DCLK (Display Clock) from CLK. The divide ratio is from 1 to 8, with reset value =0. Please refer to Product Preview Section 6.3 for the detail relationship of DCLK and CLK.
- Oscillator Frequency (A[7:4])
   Program the oscillator frequency Fosc which is the source of CLK if CLS pin is pulled HIGH. The 4-bit value results in 16 different frequency settings being available.

### 2.12 Set Second Pre-charge period (B6h)

This double byte command is used to set the phase 3 second pre-charge period. The period of phase 3 can be programmed by command B6h and it is ranged from 1 to 15 DCLK's.

# 2.13 Look Up Table for Gray Scale Pulse width (B8h, BCh, BDh)

This command is used to set each individual gray scale level of Color A, B and C for the display. Except gray scale levels GS0 that has no pre-charge and current drive, each gray scale level is programmed in the length of current drive stage pulse width with unit of DCLK. The longer the length of the pulse width, the brighter the OLED pixel when it's turned ON.

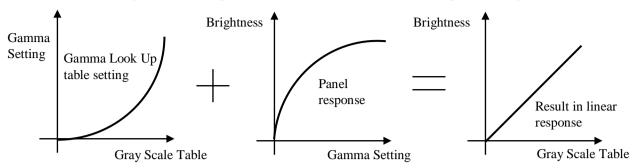
Following the command B8h, the user has to set the gray scale setting for GS1B, GS2B, ..., GS62B, GS63B one by one in sequence for LUT of color B. GS1 can be set as gamma setting 0, which means there is only pre-charge phase but no current drive phase. Refer to Product Preview Section 6.8 for details. Command B8h should be input before command BCh and BDh, to select LUT for color B, A and C.

After setting B8h command, BCh and BDh commands are used to set gray scale setting for color A and color C respectively. Following the command BCh, the user has to set the gray scale setting for GS1A, GS2A, ..., GS30A, GS31A one by one in sequence for LUT of color A. While following the command BDh, the user has to set the gray scale setting for GS1C, GS2C, ..., GS30C, GS31C one by one in sequence for LUT of color C.

The setting of gray scale table entry can perform gamma correction on OLED panel display. Since the perception of the brightness scale shall match the image data value in display data RAM, appropriate gray scale table setting like the example shown below (Figure 2-) can compensate this effect.

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Figure 2-12: Example of Gamma correction by Gamma Look Up table setting



# 2.14 Use Built-in Linear LUT (B9h)

This single byte command reloads the preset linear Gray Scale table. For color B, GS0 =Gamma Setting 0, GS1 = Gamma Setting 0, GS2 = Gamma Setting 2, GS3 = Gamma Setting 4,... GS62 = Gamma Setting 122, GS63 = Gamma Setting 124. Refer to Product Preview Section 6.8 for details.

### 2.15 Set Pre-charge voltage (BBh)

This double byte command sets the first pre-charge voltage (phase 2) level of segment pins. The level of pre-charge voltage is programmed with reference to  $V_{\rm CC}$ .

### 2.16 Set V<sub>COMH</sub> Voltage (BEh)

This double byte command sets the high voltage level of common pins,  $V_{\text{COMH}}$ . The level of  $V_{\text{COMH}}$  is programmed with reference to  $V_{\text{CC}}$ .

# 2.17 Set Contrast Current for Color A,B,C (C1h)

This command is used to set Contrast Setting of the display. The chip has 256 contrast steps from 00h to FFh. The segment output current  $I_{SEG}$  increases linearly with the contrast step, which results in brighter display.

#### 2.18 Master Contrast Current Control (C7h)

This double byte command is to control the segment output current by a scaling factor. The chip has 16 master control steps, with the factor ranges from 1 [0000b] to 16 [1111b – default]. The smaller the master current value, the dimmer the OLED panel display is set.

For example, if original segment output current is 160uA at scale factor = 16, setting scale factor to 8 would reduce the current to 80uA.

#### 2.19 Set Multiplex Ratio (CAh)

This double byte command switches default 1:128 multiplex mode to any multiplex mode from 4 to 128. For example, when multiplex ratio is set to 16, only 16 common pins are enabled. The starting and the ending of the enabled common pins are depended on the setting of "Display Offset" register programmed by command A2h. Figure 2-5 and Figure 2-6 show examples of setting the multiplex ratio through command CAh.

#### 2.20 Set Command Lock (FDh)

This command is used to lock the OLED driver IC from accepting any command except itself. After entering FDh 16h (A[2]=1b), the OLED driver IC will not respond to any newly-entered command (except FDh 12h A[2]=0b) and there will be no memory access. This is call "Lock" state. That means the OLED driver IC ignore all the commands (except FDh 12h A[2]=0b) during the "Lock" state.

Entering FDh 12h (A[2]=0b) can unlock the OLED driver IC. That means the driver IC resume from the "Lock" state. And the driver IC will then respond to the command and memory access.

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